



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-10-19
Company Unique ID	NL 008751171801		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L5050S	FFKU*UK38AA6	A	3068	2018-10-19
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	NiThPdAgAu	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	4.9-6-1.75	8	gull wing	
Comment	SO 08 STRIP SINGLE ISLAND 4+3+1			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.05	Die - Leadframe	675

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	FFKU*UK38AA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	2.087	mg	supplier	die	Silicon (Si)	7440-21-3		1.990	mg	953522	24875
				supplier	metallization	Aluminium (Al)	7429-90-5		0.013	mg	6229	163
				supplier	metallization	Tungsten (W)	7440-33-7		0.021	mg	10062	263
				supplier	Passivation	Silicon Nitride	12033-89-5		0.003	mg	1437	38
				supplier	Passivation	Silicon Oxide	7631-86-9		0.031	mg	14854	988
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.001	mg	480	13
				supplier	back side metallization	Gold (Au)	7440-57-5		0.003	mg	1437	38
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.010	mg	4792	125
Leadframe	M-004 Copper and its alloys	29.795	mg	supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.015	mg	7187	179
				supplier	alloy	Copper (Cu)	7440-50-8		29.709	mg	997114	371363
				supplier	alloy	Iron (Fe)	7439-89-6		0.030	mg	1007	375
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.009	mg	300	113
				supplier	metallization	Nickel (Ni)	7440-02-0		0.044	mg	1477	550
				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	34	13
				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	34	13
				supplier	metallization	Silver (Ag)	7440-22-4		0.001	mg	34	13
Die attach	M-015 Other organic materials	0.599	mg	supplier	glue	Silver (Ag)	7440-22-4		0.545	mg	909850	6813
				supplier	glue	acrylate	Proprietary		0.030	mg	50083	375
				supplier	glue	Methacrylate	Proprietary		0.024	mg	40067	300
Bonding wires		0.067	mg	supplier	wire	Gold (Au)	7440-57-5		0.067	mg	1000000	838
Encapsulation	M-011 Other inorganic materials	47.452	mg	supplier	mold compound	Silica, vitreous	60676-86-0		41.093	mg	865991	513663
				supplier	mold compound	Epoxy Resin	25068-38-6		3.559	mg	75002	44488
				supplier	mold compound	Phenol Resin	29690-82-2		2.373	mg	50008	29663
				supplier	mold compound	Carbon black	1333-86-4		0.237	mg	4995	2963
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.190	mg	4004	2375